



#### 5-TVS/ZENER ARRAY FOR ESD AND LATCH-UP PROTECTION

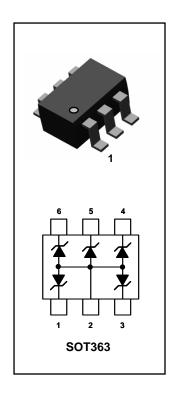
This 5-TVS/Zener Array has been designed to Protect Sensitive Equipment against ESD and to prevent Latch-Up events in CMOS circuitry, operating at 3.3V and 5V, as well available for 12V, 15V, and 24V Systems. This TVS array offers an integrated solution to protect up to 5 data lines where the board space is a premium.

#### **SPECIFICATION FEATURES**

- 100W Power Dissipation (8/20µs Waveform)
- Low Leakage Current
- Very Low Clamping Voltage
- IEC61000-4-2 ESD 20kV air, 15kV Contact Compliance
- Operating voltage options for 3.3V, 5V, 12V, 15V, and 24V
- Industry Standard SOT363 (SC70-6L) Package

#### **APPLICATIONS**

- Personal Digital Assistant (PDA)
- SIM Card Port Protection (Mobile Phone)
- Portable Instrumentation
- Mobile Phones and Accessories
- Memory Card Port Protection



#### MAXIMUM RATINGS (Per Device)

Rating	Symbol	Value	Units
Peak Pulse Power (8/20µs Waveform)	P <sub>pp</sub>	100	W
ESD Voltage (HBM)	V <sub>ESD</sub>	25	kV
Operating Temperature Range	TJ	-55 to +150	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to + 150	°C

# ELECTRICAL CHARACTERISTICS (Per Device) Tj = 25°C PJSMF03LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{WRM}$				3.3	V
Reverse Breakdown Voltage	$V_{BR}$	$I_{BR} = 10 \text{ mA}$	4.7		5.6	V
Reverse Leakage Current	I <sub>R</sub>	V <sub>R</sub> =3.3V			250	μΑ
Clamping Voltage (820µs)	V <sub>c</sub>	$I_{pp} = 5A$			7.5	V
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> = 9A			9	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			160	pF
Off State Junction Capacitance	Cj	3.3 Vdc Bias f = 1MHz Between I/O pins and pin 2			90	pF



## ELECTRICAL CHARACTERISTICS (Per Device) Tj = 25°C

# PJSMF05LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{WRM}$				5	V
Reverse Breakdown Voltage	$V_{BR}$	I <sub>BR</sub> =1mA	6.2			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>R</sub> =5V			0.5	μΑ
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> = 5A			10	V
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> = 9A			11	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			100	pF
Off State Junction Capacitance	Cj	5 Vdc Bias f = 1MHz Between I/O pins and pin 2			45	pF

## PJSMF12LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{WRM}$				12	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>BR</sub> =1mA	13.3			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>R</sub> =12V			0.5	μΑ
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> = 3A			18	V
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> = 5A			20	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			50	pF

## PJSMF15LC

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{WRM}$				15	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>BR</sub> =1mA	16.6			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>R</sub> =15V			0.5	μΑ
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> =3A			23	V
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> = 4A			25	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			40	pF





# ELECTRICAL CHARACTERISTICS (Per Device) Tj = 25°C

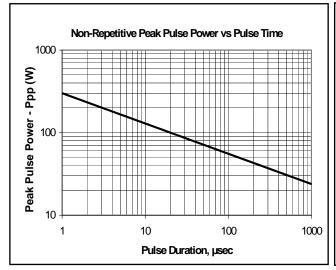
## PJSMF24LC

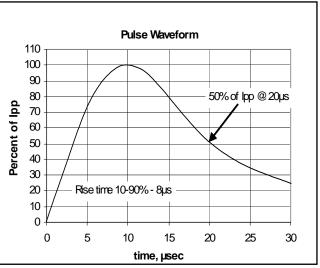
Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	$V_{WRM}$				24	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>BR</sub> =1mA	26.7			V
Reverse Leakage Current	I <sub>R</sub>	V <sub>R</sub> = 24V			0.5	μΑ
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> =1A			35	V
Clamping Voltage (8/20µs)	V <sub>c</sub>	I <sub>pp</sub> = 2A			45	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz Between I/O pins and pin 2			30	pF

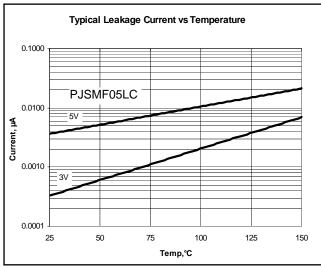


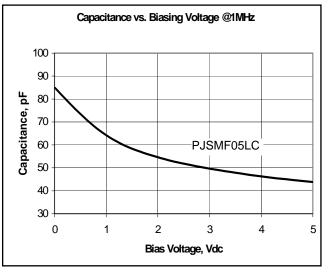


#### TYPICAL CHARACTERISTICS 25°C unless otherwise noted













### LAYOUT DIMENSIONS AND SUGGESTED PAD LAYOUT

